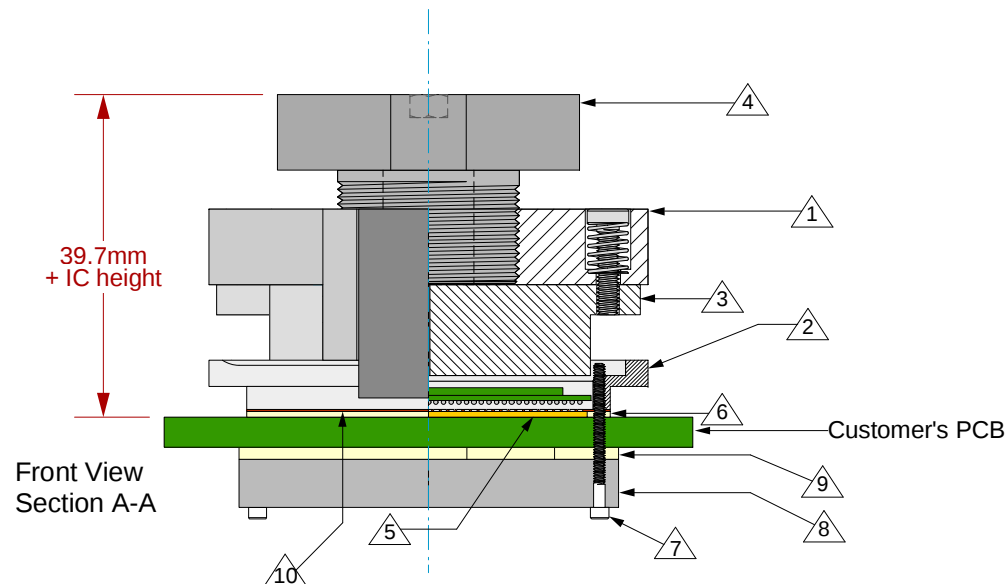
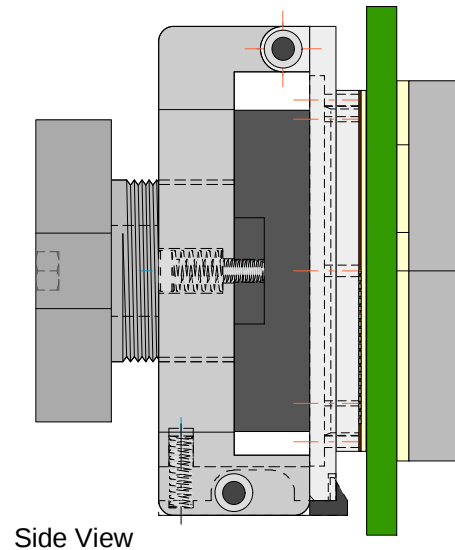
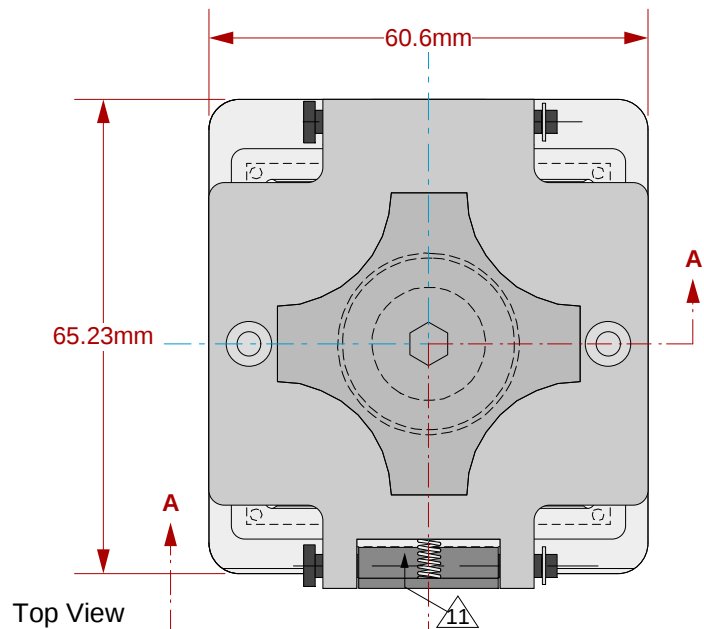




Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes evenly
- Clamshell lid

Materials:

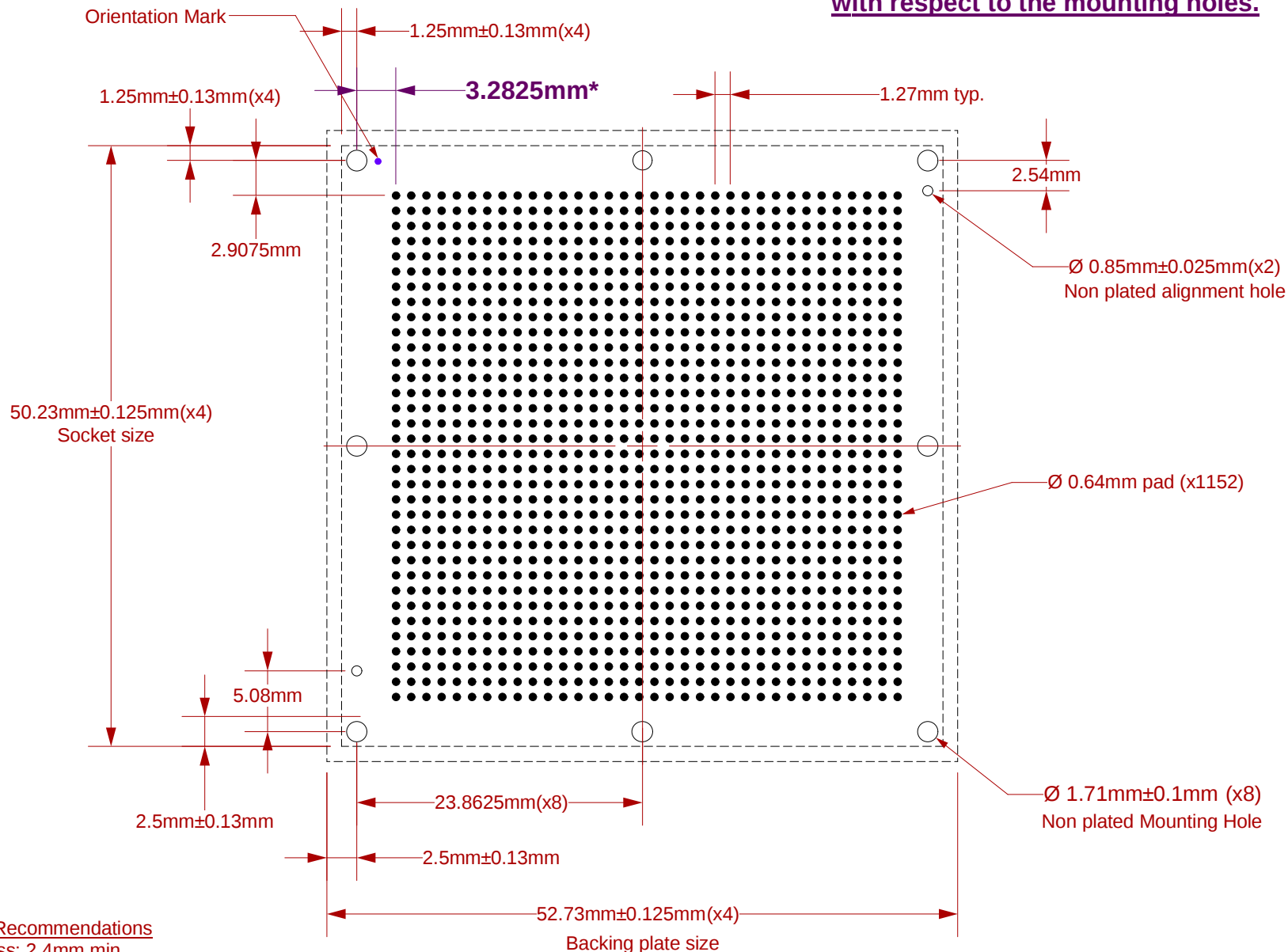
- 1 Clam Shell Lid: Black anodized Aluminum.
Height = 20 mm.
- 2 Socket Base: Black anodized Aluminum.
Height = 6 mm.
- 3 Compression Plate: Black anodized Aluminum.
Thickness = 12 mm.
- 4 Compression Screw: Clear anodized Aluminum.
Height = 27 mm, Fluted Knob
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle).
Thickness = 0.75mm.
- 6 Elastomer Guide: Non-clad FR4.
Thickness = 0.725mm.
- 7 Socket Base Screw: Socket Head Cap Screw, Black Oxide, 0-80 Thread, 5/8" long.
- 8 Backing Plate: Black anodized Aluminum
- 9 Insulation Plate: FR4/G10
- 10 Ball Guide: Kapton polyimide.
- 11 Latch: Black anodized 7075 Aluminum.

CG-BGA-4013 Drawing	Status: Released	Scale: -	Rev: A
 © 2010 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: E Smolentseva File: CG-BGA-4013 Dwg	Date: 7/14/10 Modified:	

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

***Note: BGA pattern is shifted to the right by 0.375mm with respect to the mounting holes.**



Target PCB Recommendations

Total thickness: 2.4mm min.

Plating: Gold or Solder finish

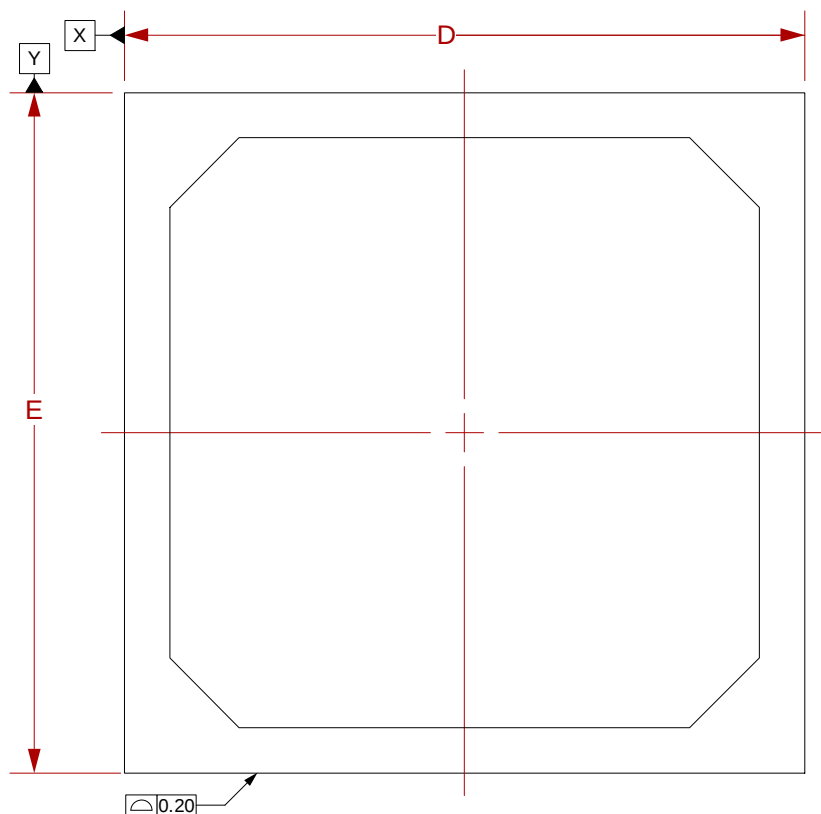
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

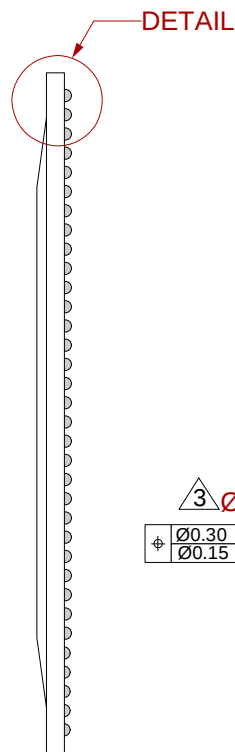
Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001"$] unless stated otherwise.

CG-BGA-4013 Drawing	Status: Released	Scale: -	Rev: A
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	File: CG-BGA-4013 Dwg	Modified:	

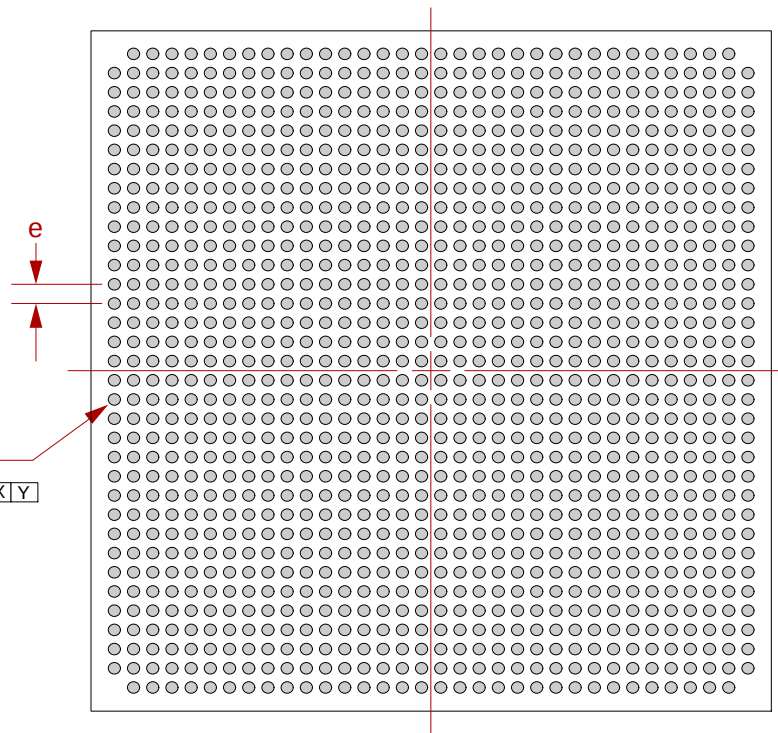
Compatible BGA Spec



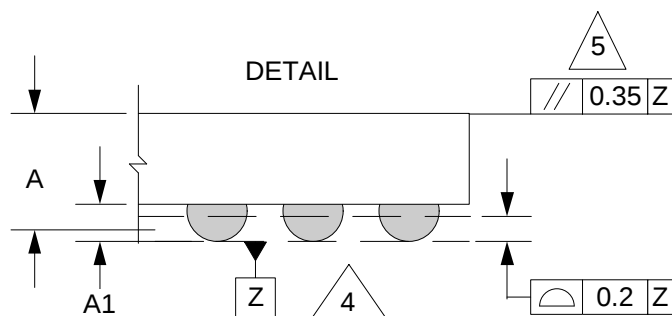
TOP VIEW



SIDE VIEW



BOTTOM VIEW



1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.51
A1	0.5	0.7
b		0.90
D	45 BSC	
E	45 BSC	
e	1.27 BSC	

Array: 34 x 34

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